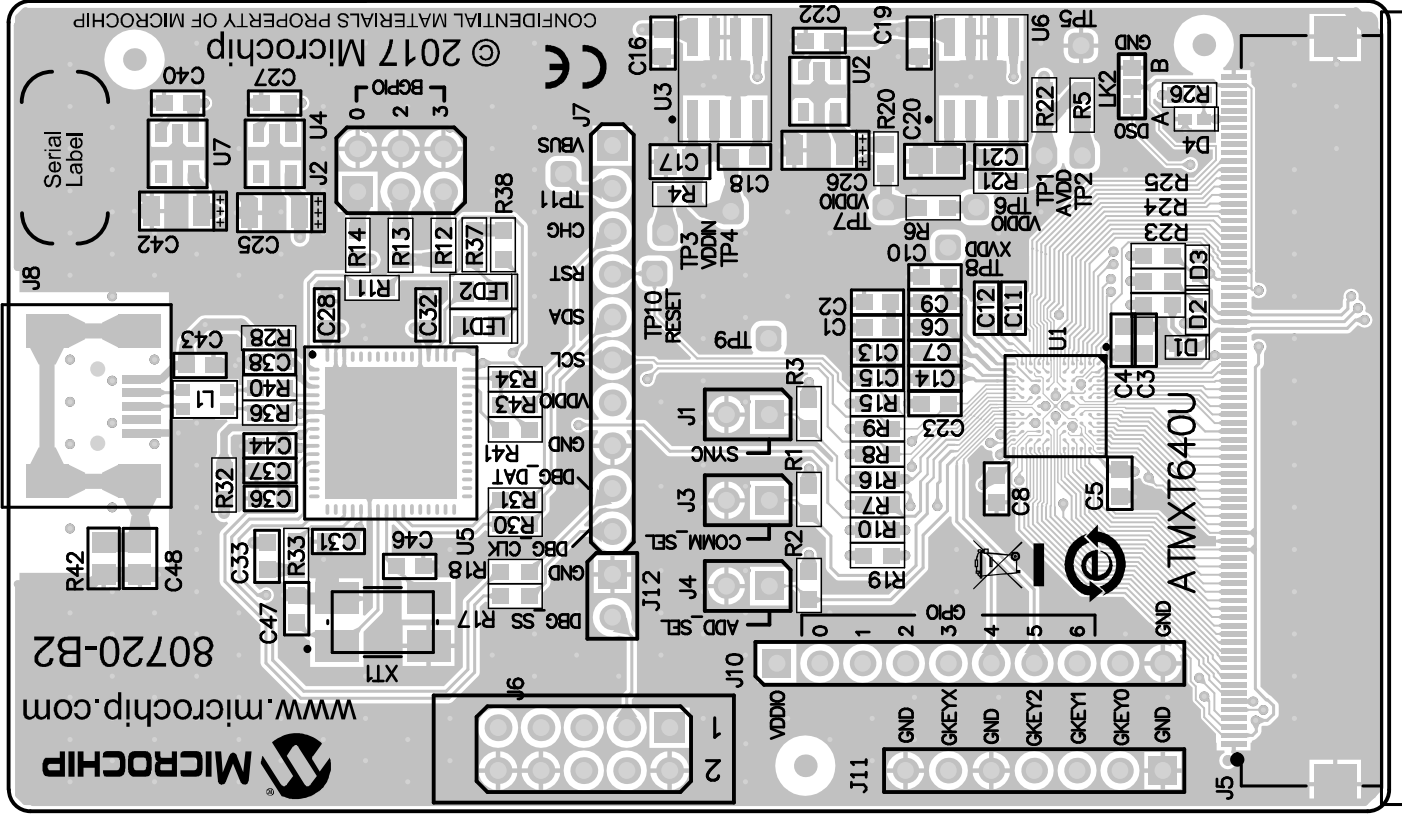
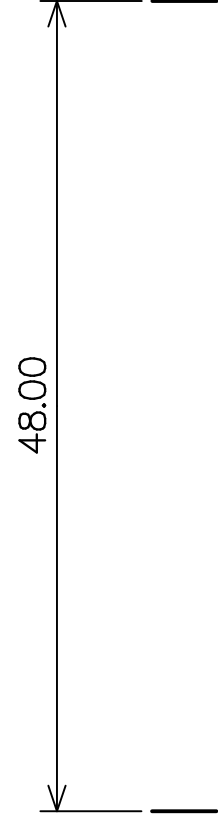




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Title: mXT640U EVK Board				Layer BOARD OUTLINE		
Number: 80720		Iss: B2		ECN: N/A		
Dm: P.Cassidy		Chk'd:		App'd: CAD:		
Design created from schematic: B-2835-B1						
Date: 20th April 2018		Filename: 80720.PcbDoc				
 MICROCHIP		This version supercedes all other versions. Please destroy all previous versions.				
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Iss	Notes			ECN	Dm	Date
A0	First Issue			N/A	DC	5th May 2015
B0	Changed U1 Ball/Pin H7,L7,K7			N/A	MD	17th June 2015
B1	Changed to MCHP format			N/A	PFC	12th June 2017
B2	RoHS, WEEE & CE symbols added			N/A	PFC	20th April 2018

Material: FR-4 1.6mm 4 layer PTH, 35um copper

Finish: ENIG (Electroless Nickel Immersion Gold)

Solder mask both sides in BLACK

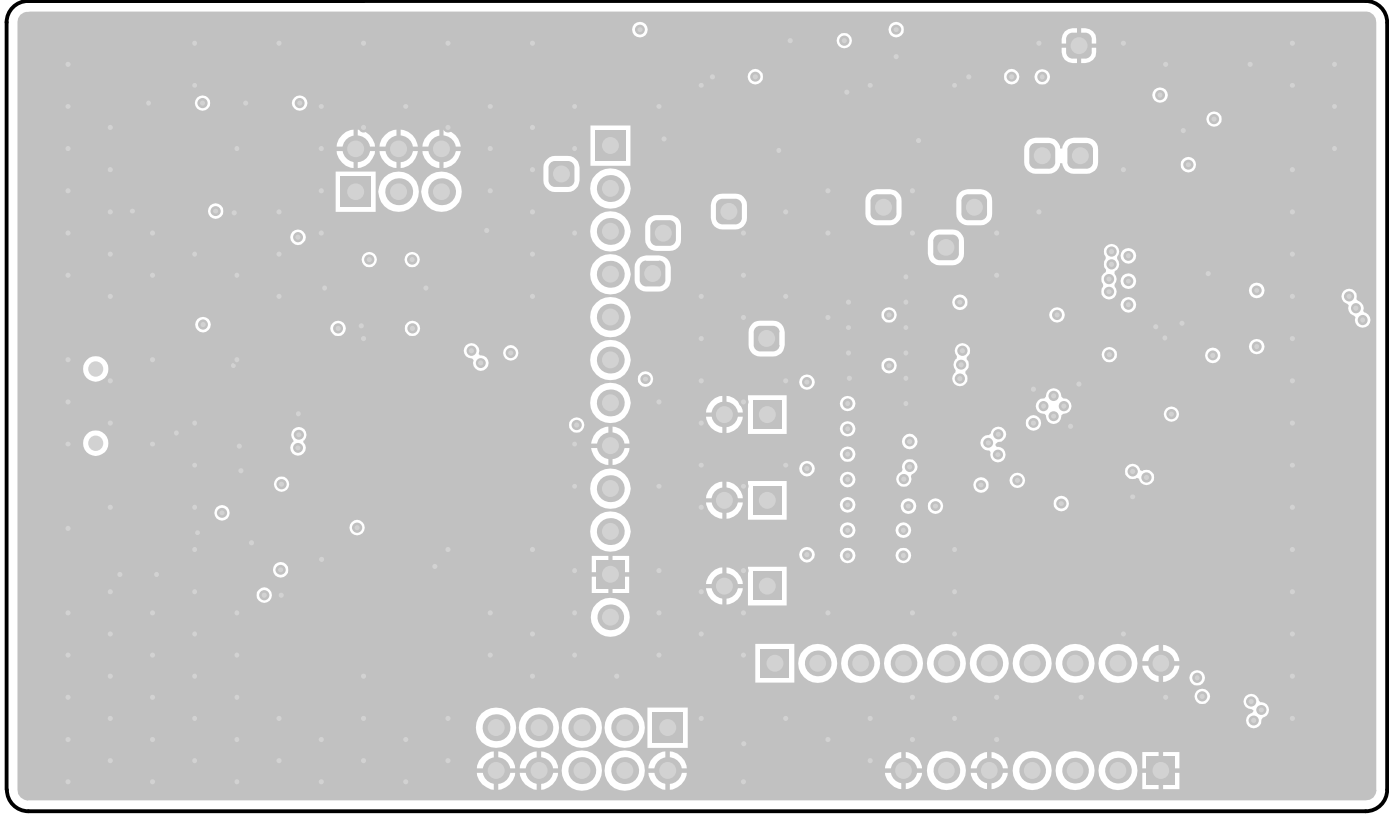
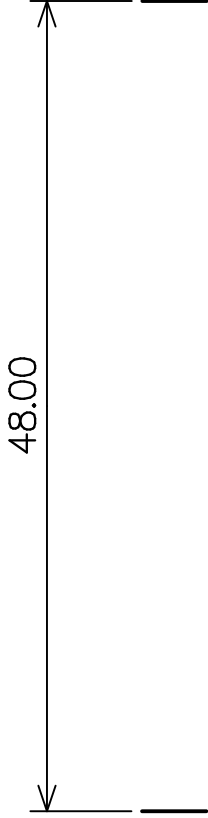
Silkscreen top side in WHITE

All dimensions in millimetres

View on top (component) side

All components and materials used must be RoHS compliant as described in European Parliament Directive 2002/95/EC

Symbol	Count	Hole Size	Plated	Hole Type
◇	2	0.900mm (35.43mil)	NPTH	Round
⊞	62	1.000mm (39.37mil)	PTH	Round
◎	321	0.300mm (11.81mil)	PTH	Round
	385 Total			



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Title: mXT640U EVK Board				Layer BOARD OUTLINE		
Number: 80720		Iss: B2		ECN: N/A		
Dm: P.Cassidy		Chk'd:		App'd: CAD:		
Design created from schematic: B-2835-B1						
Date: 20th April 2018		Filename: 80720.PcbDoc				
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Iss	Notes			ECN	Dm	Date
A0	First Issue			N/A	DC	5th May 2015
B0	Changed U1 Ball/Pin H7,L7,K7			N/A	MD	17th June 2015
B1	Changed to MCHP format			N/A	PFC	12th June 2017
B2	RoHS, WEEE & CE symbols added			N/A	PFC	20th April 2018

Material: FR-4 1.6mm 4 layer PTH, 35um copper

Finish: ENIG (Electroless Nickel Immersion Gold)

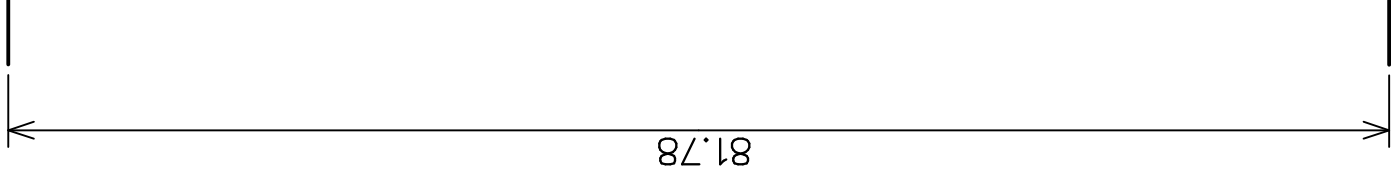
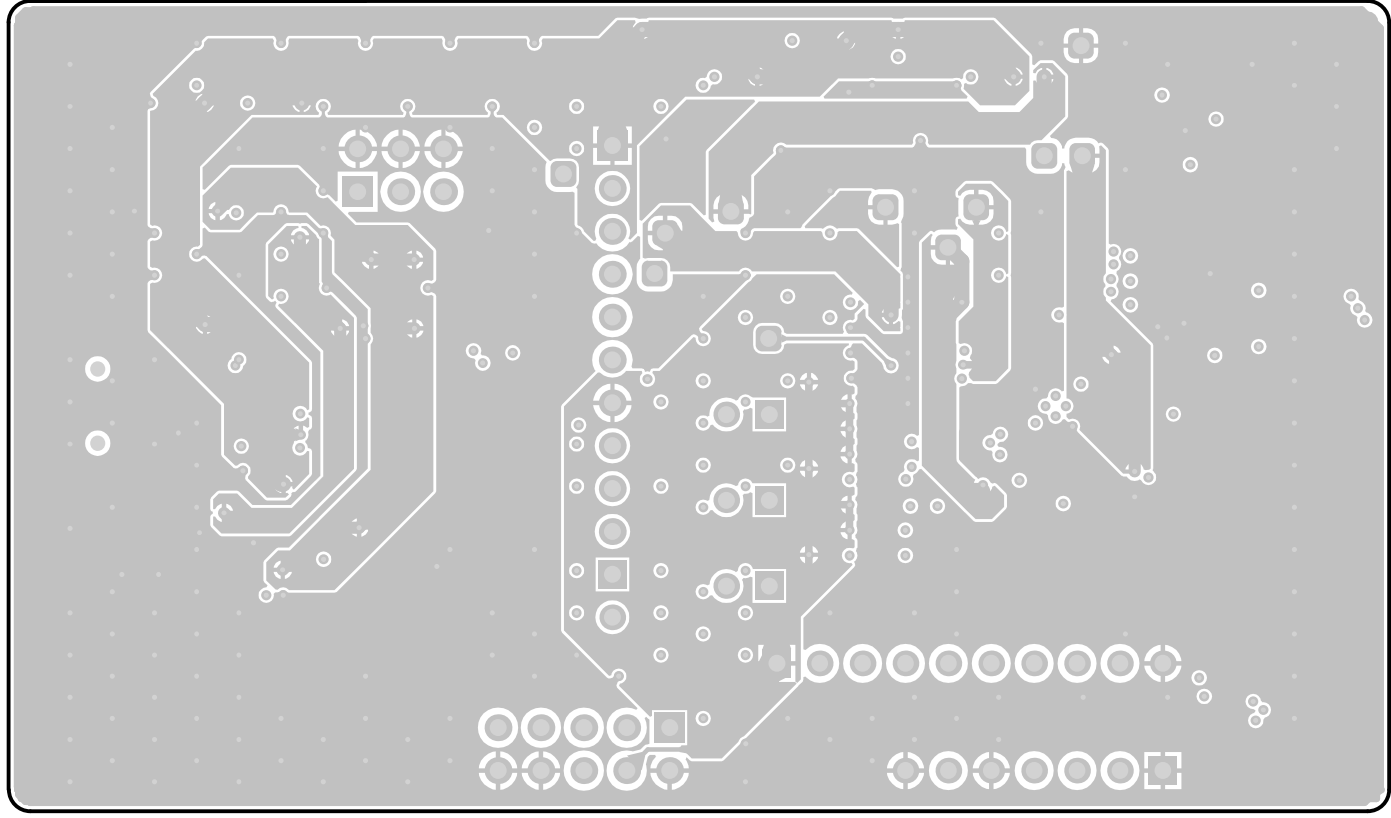
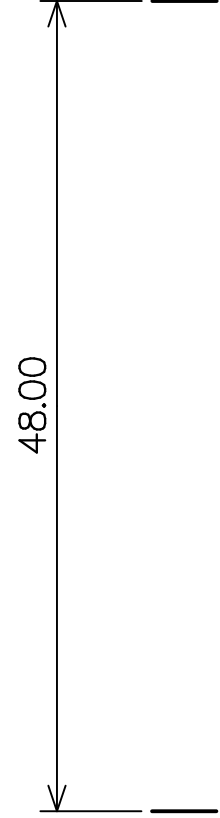
Solder mask both sides in BLACK

Silkscreen top side in WHITE

All dimensions in millimetres

View on top (component) side

All components and materials used must be RoHS compliant as described in European Parliament Directive 2002/95/EC



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Title: mXT640U EVK Board				Layer BOARD OUTLINE		
Number: 80720		Iss: B2		ECN: N/A		
Dm: P.Cassidy		Chk'd:		App'd: CAD:		
Design created from schematic: B-2835-B1						
Date: 20th April 2018		Filename: 80720.PcbDoc				
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Iss	Notes			ECN	Dm	Date
A0	First Issue			N/A	DC	5th May 2015
B0	Changed U1 Ball/Pin H7,L7,K7			N/A	MD	17th June 2015
B1	Changed to MCHP format			N/A	PFC	12th June 2017
B2	RoHS, WEEE & CE symbols added			N/A	PFC	20th April 2018

Material: FR-4 1.6mm 4 layer PTH, 35um copper

Finish: ENIG (Electroless Nickel Immersion Gold)

Solder mask both sides in BLACK

Silkscreen top side in WHITE

All dimensions in millimetres

View on top (component) side

All components and materials used must be RoHS compliant as described in European Parliament Directive 2002/95/EC

as described in European Parliament Directive 2005/62/EC
All components and materials used must be RoHS compliant

View on top (component) side

All dimensions in millimetres

Silkscreen top side in WHITE

Solder mask both sides in BLACK

Finishing: ENIG (Electroless Nickel Immersion Gold)

Material: FR-4 prepreg 4 mm thick, 1.4 mm copper

B5	ROH2' WEEE & CE symposia added	N/A	BFC	50th April 2018
B1	Changed to MCHP format	N/A	BFC	15th June 2017
B0	Changed U1 Bqll\pin H2'T2'K2	N/A	MD	17th June 2012
A0	First issue	N/A	DC	2th May 2012
as	Notes	ECN	Dm	Date

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Date: 50th April 2018		Please destroy all previous versions. This version supersedes all other versions.	
Design created from schematic: B-5832-B1		Filename: 80250.PcpDoc	
P.Cassidy	CHK,q:	Abb,q:	CAD:
Number: 80250	Iss: B5	ECN: N/A	
Title: MXT640N EVK Board		BOARD OUTLINE Layer	
		BOTTOM COPPER	

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